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(12) **United States Patent**  
**Yang**

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(54) **SUPPLY MECHANISM FOR THE CHUCK OF AN INTEGRATED CIRCUIT DICING DEVICE**

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See application file for complete search history.

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(57) **ABSTRACT**

A system for dicing substrates to singulate integrated circuit units within in them includes a dicing machine (Z) which operates with a chuck table (4). A lifting assembly (Ax,Ay) deposits substrates to be singulated onto the chuck table (4) at substantially the same time as it removes previously singulated units from the chuck table (4).

**5 Claims, 23 Drawing Sheets**

